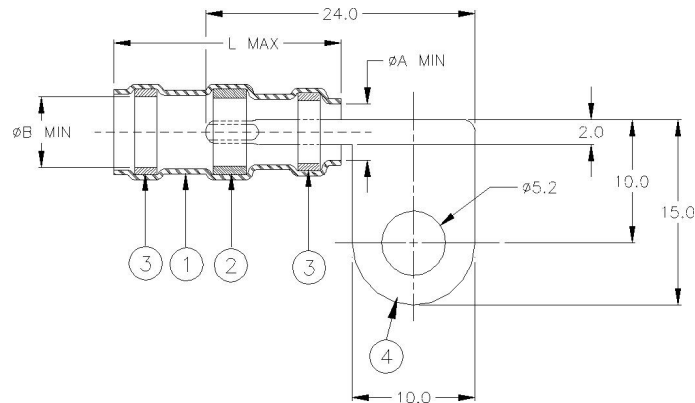


B-150-05-F and B-150-07-F, Solder sleeves with flag



| Product Name | Product Dimensions | | | Cable Dimensions | | |
|--------------|--------------------|----------------|-----------------|------------------|----------------|--------------------|
| | øA min | øB min | L max | øE min | øG max | J 0.5 (J±0.020) |
| B-150-05-F | 4.3 (0.169) | 4.8 (0.189) | 18.5 (0.728) | 2.0 (0.078) | 4.3 (0.169) | 6.5 (0.256) |
| B-150-07-F | 6.8 (0.267) | 7.3 (0.287) | 21.0 (0.827) | 3.3 (0.130) | 6.8 (0.267) | 8.0 (0.315) |

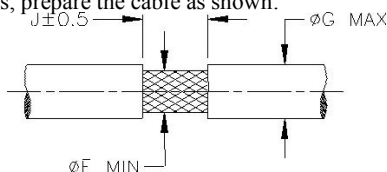
MATERIALS

- INSULATION SLEEVE: Heat-shrinkable, transparent clear, radiation cross-linked modified polyolefin.
- SOLDER PREFORM WITH FLUX.
SOLDER: TYPE Cd18 per ANSI-J-STD-006.
FLUX: TYPE ROM1 per ANSI-J-STD-004.
- MELTABLE SEALING RINGS: Thermally stabilized thermoplastic.
- GROUNDING BAR: Tin plated brass alloy.


APPLICATION

- These controlled soldering, grounding devices are designed for termination of a bare or tin plated copper shield on a cable having an insulation rated for at least +85 C.
- Temperature range: -55 C to +125 C.
- For installation procedure and application equipment, consult RPIP-688-02.

For best results, prepare the cable as shown:



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| | | | | | |
|--|---|---|----------------|---|----------------------------------|
|  | | Raychem THERMOFIT DEVICES | | TITLE: SOLDERSLEEVE WITH FLAG TERMINAL | |
| UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS. INCHES DIMENSIONS ARE BETWEEN BRACKETS. | | | | DOCUMENT NO: B-150-XX-F | |
| TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A | ANGLES: N/A ROUGHNESS IN MICRON | TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application. | | Revision: 2 | Issue Date: April 2020 |
| PREPARED BY: M. FORONDA | DATE: 10/20/99 | ECO: ECO-20-004959 | SCALE: None | SIZE: A | SHEET: 1 of 1 |